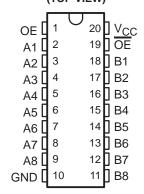
- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

description/ordering information

The SN74CBT3345 provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch bank with dual output-enable (OE and \overline{OE}) inputs. When \overline{OE} is low or OE is high, the switch is on, and port A is connected to port B. When \overline{OE} is high and OE is low, the switch is open, and the high-impedance state exists between the two ports.

DB, DBQ, DGV, DW, OR PW PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE†		PACKAGET ORDERABLE PART NUMBER	
	0010 DW	Tube	SN74CBT3345DW	ODT0045
–40°C to 85°C	SOIC - DW	Tape and reel	SN74CBT3345DWR	CBT3345
	SSOP – DB	Tape and reel	SN74CBT3345DBR	CU345
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3345DBQR	CBT3345
	TOOOD DW	Tube	SN74CBT3345PW	011045
	TSSOP – PW	Tape and reel	SN74CBT3345PWR	CU345
	TVSOP – DGV	Tape and reel	SN74CBT3345DGVR	CU345

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

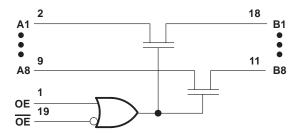
INP	UTS	FUNCTION	
OE	OE		
Н	Х	A port = B port	
Х	L	A port = B port	
L	Н	Disconnect	



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Continuous channel current		
Input clamp current, I_{IK} ($V_{I/O}$ < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	70°C
	DBQ package	68°C
	DGV package	92°C
	DW package	58°C
	PW package	83°C
Storage temperature range, T _{sta}		. –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
V_{IH}	High-level control input voltage	2		V
VIL	Low-level control input voltage		8.0	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
II	All inputs	$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ
ICC		$V_{CC} = 5.5 \text{ V},$	I _O = 0,	$V_I = V_{CC}$ or GND			50	μΑ
Δl _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			3.5	mA
Ci	Control inputs	V _I = 3 V or 0				3		pF
C _{io(OFF)}		$V_{O} = 3 \text{ V or } 0,$	$\overline{OE} = V_{CC}$ or $OE = GI$	ND		6		pF
r _{on} §		$V_{CC} = 4.5 \text{ V}$ $V_{I} = 0$ $V_{I} = 2.4 \text{ V},$		I _I = 64 mA		5	7	
			I _I = 30 mA		5	7	Ω	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

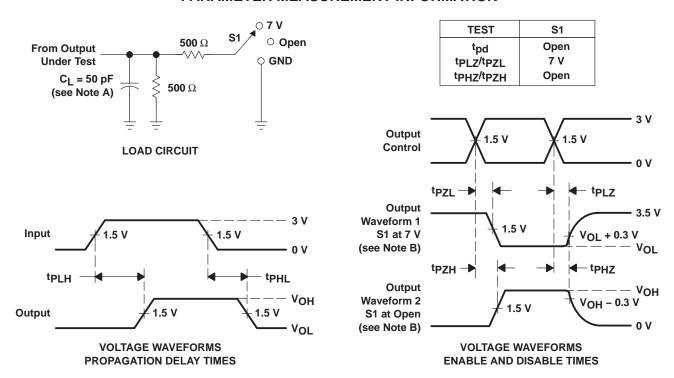
PARAMETER	FROM	TO	V _{CC} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	
$t_{pd}\P$	A or B	B or A		0.25	ns
t _{en}	OE or OE	A or B	1	9.1	ns
^t dis	OE or OE	A or B	1	8.7	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



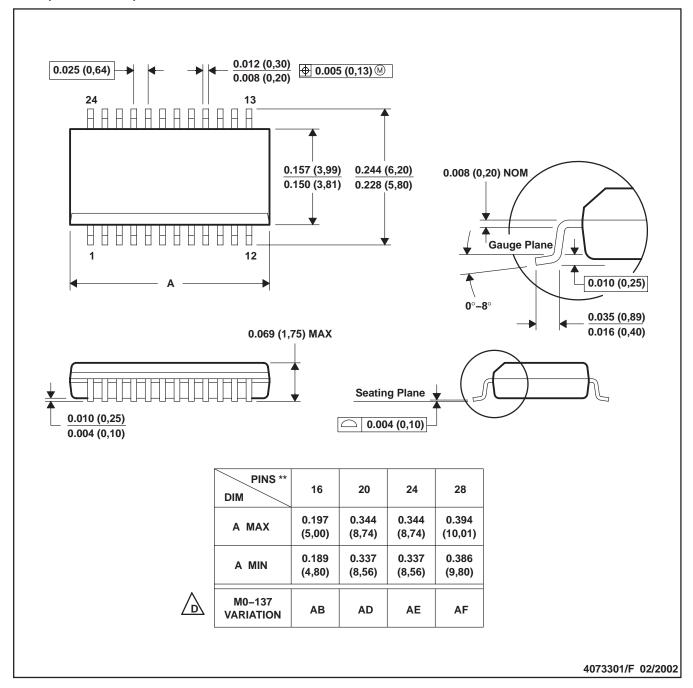
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DBQ (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-137.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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